Effective June 2014 Supersedes November 2011

Coiltronics HCM0503 Series High current power inductors



Product description

- · High current carrying capacity
- · Low core losses
- · Magnetically shielded, low EMI
- Frequency range up to 1MHz
- Inductance range from 0.20µH to 15µH
- Current range from 2.1A to 22.2A
- 5.5 x 5.3mm footprint surface mount package in a 3mm height
- Powder Iron core material
- · Halogen free, lead free, RoHS compliant

Applications

- Voltage Regulator Module (VRM)
- Multi-phase regulators
- · Point-of-load modules
- · Desktop and server VRMs and EVRDs
- · Base station equipment
- Notebook regulators
- Battery power systems
- · Graphics cards
- · Data networking and storage systems

Environmental data

- Storage temperature range (Component): -55°C to +125°C
- Operating temperature range: -55°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant





Coiltronics is now part of Eaton Same great products plus even more.



The Coiltronics brand of magnetics (formerly of the Bussmann Division of Cooper Industries) is now part of Eaton's Electrical Group, Electronics Division.

Product specifications

Part Number ⁶	OCL ¹ (μH) ± 20%	FLL min.² (µH)	l _{rms} ³ (Amps)	l _{sat} ⁴ (Amps)	DCR (mΩ) @ 20°C (Typ.)	DCR (mΩ) @ 20°C (Max.)	K-factor⁵
HCM0503-R20-R	0.20	0.128	22.2	21.0	2.10	2.31	1764
HCM0503-R35-R	0.35	0.224	16.6	14.9	3.90	4.29	1259
HCM0503-R47-R	0.47	0.300	12.0	11.5	6.50	7.15	820
HCM0503-R75-R	0.75	0.480	11.3	9.7	8.50	9.35	801
HCM0503-1R0-R	1.00	0.640	10.1	8.5	10.4	11.4	588
HCM0503-1R5-R	1.50	0.960	7.5	7.0	17.1	18.5	393
HCM0503-2R2-R	2.20	1.40	6.8	6.5	22.5	25.0	325
HCM0503-3R3-R	3.30	2.10	5.5	6.0	36.4	40.4	273
HCM0503-4R7-R	4.70	3.00	4.5	5.5	54.0	60.0	226
HCM0503-5R6-R	5.60	3.60	4.3	3.5	63.0	70.6	206
HCM0503-100-R	10.0	6.40	2.8	2.3	122	132	158
HCM0503-150-R	15.0	9.60	2.4	2.1	138	166	127

1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, $0.25V_{\rm rms'}$ 0.0Adc, +25°C.

2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.25V_{rms}, I_{sat}, @ +25°C.

3.1_{rms}: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application. 4. I_{sat}: Peak current for approximately 20% rolloff at +25°C.

5. K-factor: Used to determine $B_{_{P^{p}}}$ for core loss (see graph). $B_{_{P^{p}}} = K * L * \Delta I.$ $B_{_{P^{p}}}$ (Gauss), K: (K-factor from table), L: (Inductance in μH), ΔI (Peak to peak ripple current in amps).

6. Part Number Definition: HCM0503-yyy-R

- yyy= Inductance value in µH, R = decimal point,

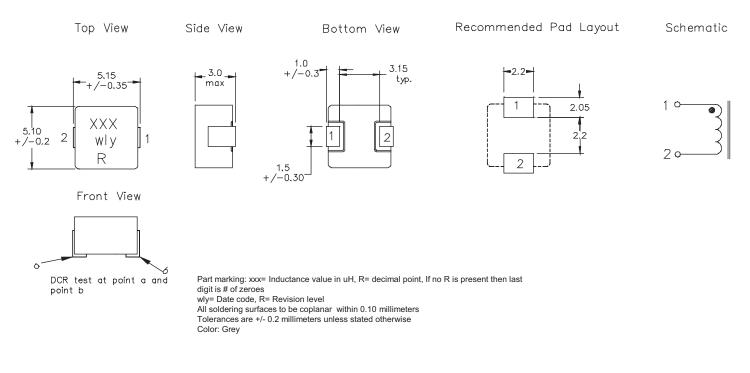
if no R is present then third character = number of zeros.

- "-R" suffix = RoHS compliant

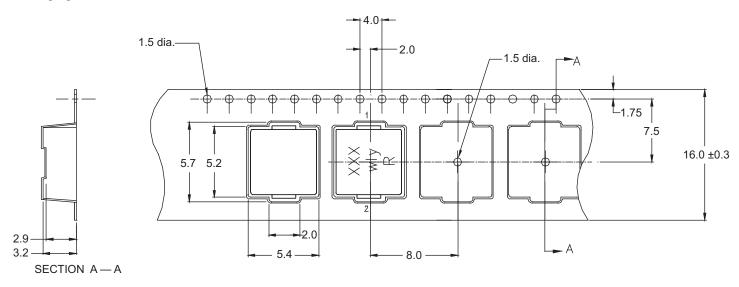
⁻ HCM0503 = Product code and size

HCM0503 Series High current, power inductors

Dimensions - mm



Packaging information - mm



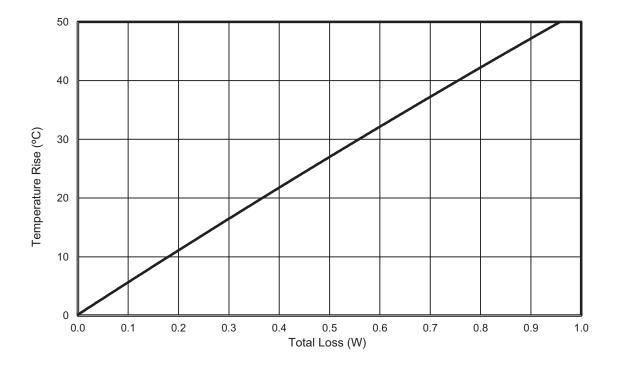
Supplied in tape and reel packaging, 2000 parts per 13" diameter reel.

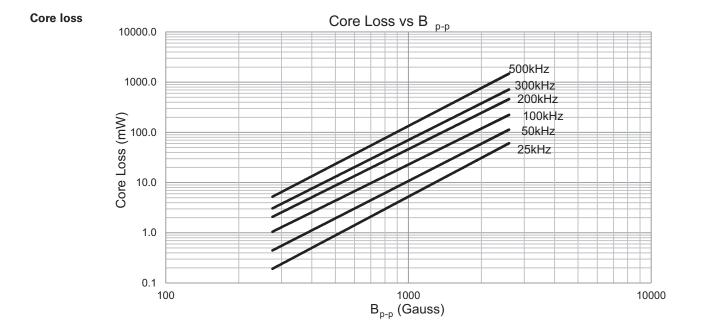
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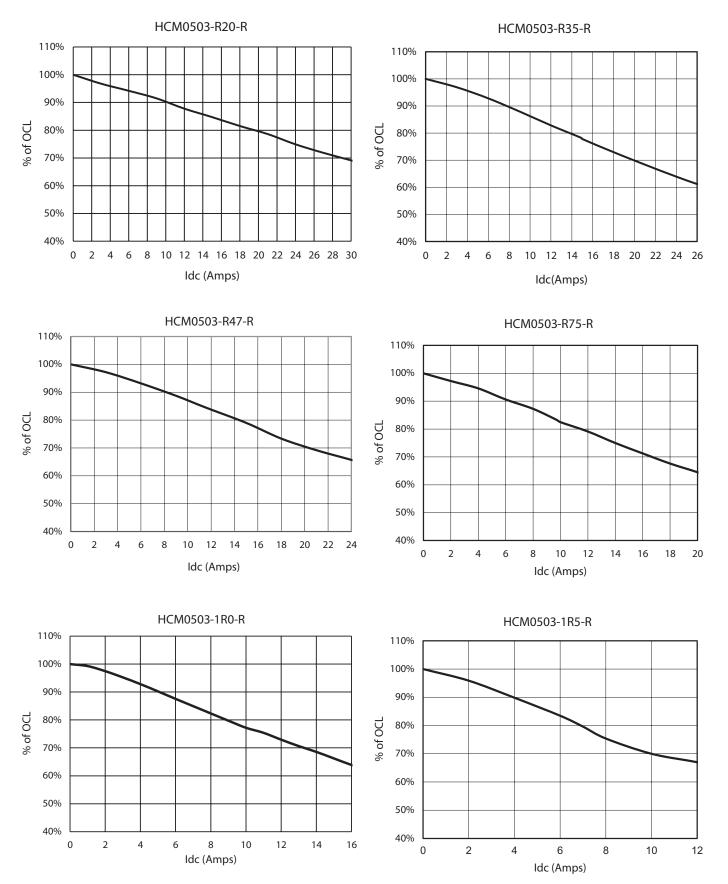
Temperature rise vs. total loss



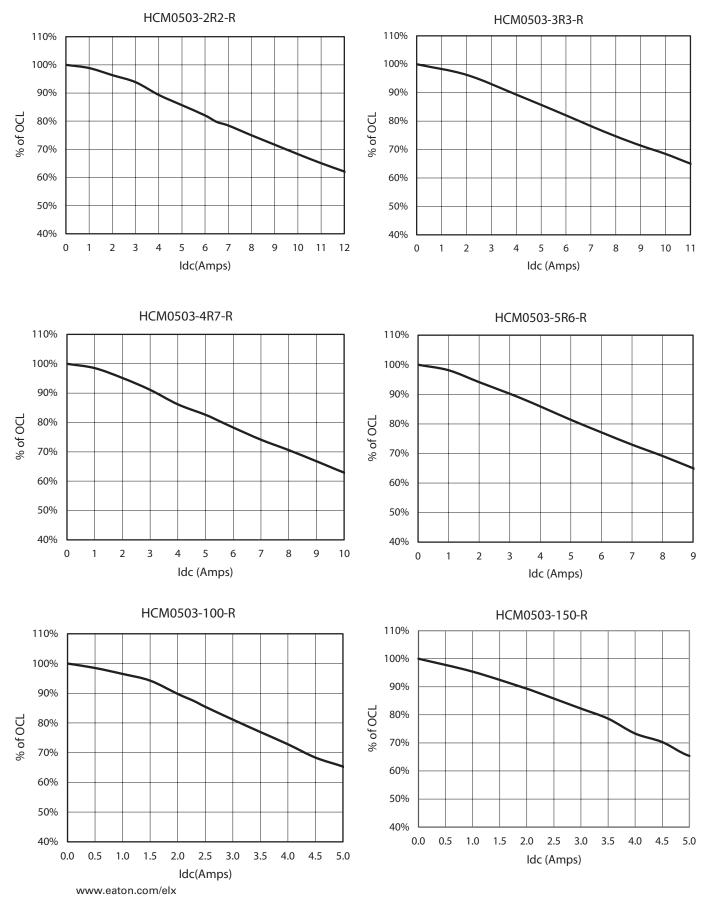


HCM0503 Series High current, power inductors

Inductance characteristics



Inductance characteristics



HCM0503 Series High current, power inductors

Solder reflow profile

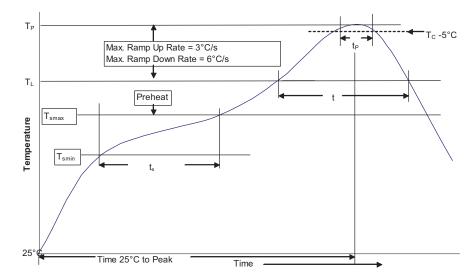


Table I - St	anuaru Shpi	o Solder (1 _C)
	Volume	Volume
Package	mm ³	mm ³
Thickness	<350	≥350
<2.5mm	235°C	220°C
≥2.5mm	220°C	220°C

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Table 2 - Lead (Pb) Free Solder (T_c)

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Deelvoge	Volume	Volume mm ³	Volume mm ³
Package	mm³	mm	IIIII
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JDEC J-STD-020D

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder	
Preheat and Soak	 Temperature min. (T_{smin}) 	100°C	150°C	
	 Temperature max. (T_{smax}) 	150°C	200°C	
	 Time (T_{smin} to T_{smax}) (t_s) 	60-120 Seconds	60-120 Seconds	
Average ramp up rate T _{smax} to T _p		3°C/ Second Max.	3°C/ Second Max.	
Liquidous temperature (TL)		183°C	217°C	
Time at liquidous (t _L)		60-150 Seconds	60-150 Seconds	
Peak package body temperature (T _P)*		Table 1	Table 2	
Time $(t_p)^{\star\star}$ within 5 °C of the specified classification temperature (T_c)		20 Seconds**	30 Seconds**	
Average ramp-down rate (Tp to Tsmax)		6°C/ Second Max.	6°C/ Second Max.	
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.	

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (tp) is defined as a supplier minimum and a user maximum.

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